

WHAT IS CLAIMED IS:

1. A method of manufacturing a laminated ceramic electronic component comprising the steps of:

preparing a first transfer sheet including a composite green sheet supported by a first supporting film, said composite green sheet having a conductor and at least one of a first ceramic area and a second ceramic area formed in a region excluding a location where the conductor is provided;

preparing a second transfer sheet including a ceramic green sheet supported by a second supporting film;

a first transfer step of transferring the ceramic green sheet of at least one second transfer sheet on a lamination stage;

a second transfer step of transferring the composite green sheet of at least one first transfer sheet on the at least one ceramic green sheet that was previously laminated;

a third transfer step of transferring the ceramic green sheet of at least one second transfer sheet on the composite green sheet that was previously laminated; and

firing a laminate obtained by the first, second and third transfer steps.

2. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein a plurality of the first transfer sheets are prepared, and the

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conductors are formed so that by laminating, the conductors of the plurality of the composite green sheets are electrically connected to form a coil.

3. A method of manufacturing a laminated ceramic electronic component according to claim 2, wherein at least one of the plurality of the conductors is a via hole electrode for connecting the upper and lower conductors.

4. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the first ceramic area is made of a magnetic ceramic, and a second ceramic area is made of a non-magnetic ceramic.

5. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the ceramic green sheet of the second transfer sheet is made of a magnetic ceramic.

6. A method of manufacturing a laminated ceramic electronic component according to claim 4, further comprising the step of forming the first ceramic area and the second ceramic area by printing a magnetic ceramic paste and a non-magnetic ceramic paste, respectively.

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7. A method of manufacturing a laminated ceramic electronic component according to claim 3, further comprising the steps of:

forming the at least one of the first ceramic area and the at least one second ceramic area at a location excluding a region where a via hole electrode is to be formed; and

thereafter filling the region where the via hole is to be formed with an electrically conductive paste to form the via hole electrode.

8. A method of manufacturing a laminated ceramic electronic component according to claim 3, further comprising the steps of:

forming a through hole in which a via hole electrode is to be formed after preparing the composite ceramic green sheet; and

filling the through hole with an electrically conductive paste to form the via hole electrode.

9. A method of manufacturing a laminated ceramic electronic component according to claim 1, further comprising the steps of:

preparing a third transfer sheet in which a second composite green sheet having a magnetic ceramic area and a non-magnetic ceramic area is supported by a third supporting

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film; and

transferring the second composite green sheet from at least one third transfer sheet between the first transfer step and the third transfer step.

10. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the laminated ceramic electronic component is a closed magnetic circuit type laminated common mode choke coil.

11. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil.

12. A laminated ceramic electronic component comprising a sintered ceramic body produced according to the method as set forth in claim 1, and a plurality of external electrodes disposed on the outer surface of the sintered ceramic body and electrically connected to the conductors in the sintered ceramic body.

13. A laminated ceramic electronic component according to claim 12, wherein the laminated ceramic electronic component is a closed magnetic circuit type laminated common

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mode choke coil.

14. A laminated ceramic electronic component according to claim 12, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil.

15. A laminated ceramic electronic component comprising:

a sintered ceramic body;

at least one coil conductor arranged in the sintered ceramic body and having a winding portion and first and second lead-out portions; and

a plurality of external electrodes disposed on the outer surface of the sintered ceramic body and electrically connected to an end of the first lead-out portion or an end of the second lead-out portion;

wherein the sintered ceramic body includes a magnetic ceramic and a non-magnetic ceramic, the winding portion of the coil conductor is coated with the non-magnetic ceramic, and the first and second lead-out portions of the coil conductor are coated with the non-magnetic ceramic.

16. A laminated ceramic electronic component according to claim 15, wherein the laminated ceramic electronic

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component is a closed magnetic circuit type laminated common mode choke coil.

17. A laminated ceramic electronic component according to claim 15, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil.

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